

ABSTRACT OF THE DISCLOSURE

A semiconductor package with a thermal enhance film mainly comprises a substrate, a semiconductor chip and a thermal enhance film. The semiconductor chip is electrically connected to the substrate and the thermal enhance film is formed on the back surface of the semiconductor chip. Therein, the thermal enhance film can be regarded as a heat transmission layer to transmit the heat to the outside and upgrade the thermal efficiency of the semiconductor package. In addition, the thermal enhance film can be made of a material comprising polymer. For example, the thermal enhance film is a thermally conductive polymer layer and can be regarded as a buffer layer to prevent the active surface of the semiconductor chip from being chipped. Furthermore, a manufacturing method to manufacture the semiconductor package is provided.